DATA SHEET

Part No.	AN5891K
Package Code No.	SDIP024-P-0300B

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AN5891K

TV and audio sound processor

■ Features

- Sound Processor using I²C bus
- This IC has Mute, AGC, super bass, tone, volume balance control, and 3-D surround.

■ Applications

• TV, Audio

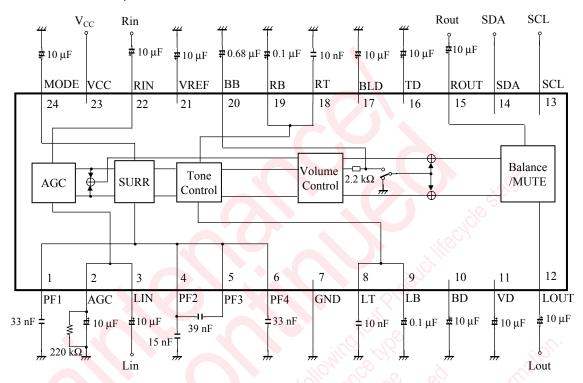
■ Package

• 24 pin Plastic Shrink Dual Inline Package (SDIP Type)

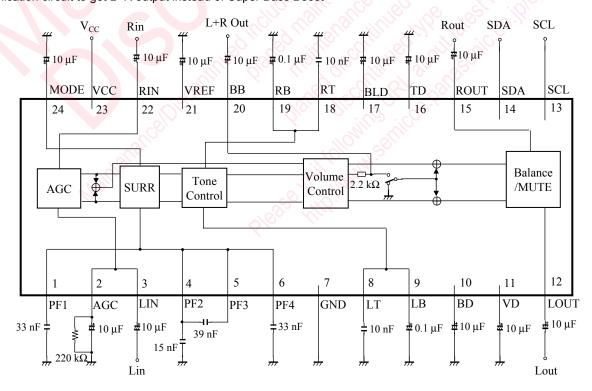
■ Type

• Silicon monolithic bipolar IC

■ Application Circuit Example



Application circuit to get L+R output instead of Super Bass Boost

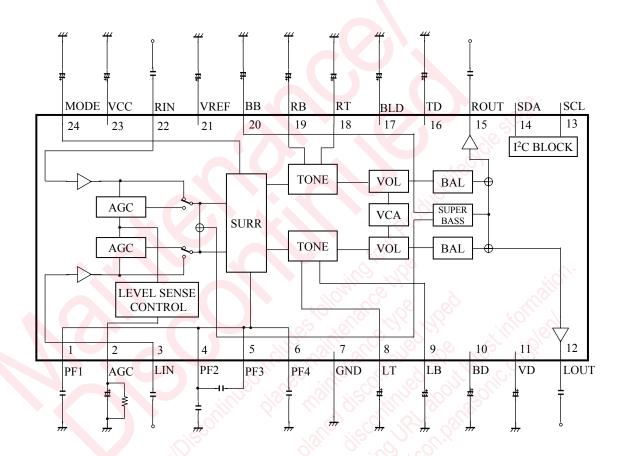


Note) This application circuit is shown as an example but does not guarantee the design for mass production set.

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■ Block Diagram

AN5891K



Note) This block diagram is for explaining functions. The part of the block diagram may be omitted, or it may be simplified.

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■ Pin Descriptions

Pin No.	Pin name	Description
1	PF1	Phase filter 1
2	AGC	AGC level sensor
3	LIN	L-ch. input
4	PF2	Phase filter 2
5	PF3	Phase filter 3
6	PF4	Phase filter 4
7	GND	Ground
8	LT	L-ch. treble Fc adjustment
9	LB	L-ch. bass Fc adjustment
10	BD	BASS DAC output
11	VD	Volume DAC output
12	LOUT	L-ch. output
13	SCL	SCL
14	SDA	SDA
15	ROUT	R-ch. output
16	TD	Treble DAC output
17	BLD	Balance DAC output
18	RT	R-ch. treble Fc adjustment
19	RB	R-ch. bass Fc adjustment
20	BB	Bass mixer gain adjustment
21	VREF	1/2V _{CC}
22	RIN	R-ch. input
23	VCC	Power supply pin (V _{CC})
24	MODE	Mode control

■ Absolute Maximum Ratings

Note) Absolute maximum ratings are limit values which are not destructed, and are not the values to which operation is guaranteed.

A No.	Parameter	Symbol	Rating	Unit	Notes
1	Supply voltage	V _{CC}	11.0	V	*1
2	Supply current	I_{CC}	50	mA	_
3	Power dissipation	P_{D}	550	mW	_
4	Operating ambient temperature	T _{opr}	-25 to +75	°C	*2
5	Storage temperature	T _{stg}	-55 to +150	°C	*2

Notes) *1: The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

■ Operating Supply Voltage Range

Parameter	Symbol	Range	Unit	Notes
Supply voltage range	V _{CC}	6.0 to 10.0	V	*

Note) *: The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

^{*2 :} Except for the power dissipation, operating ambient temperature, and storage temperature, all ratings are for T_a = 25°C.

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■ Electrical Characteristics at V_{CC} = 9.0 V Note) T_a = 25°C±2°C unless otherwise specified.

B	D .		0 177		Limits	Linit		
No.	Parameter	Symbol	Conditions	Min	Тур	Max Unit		Notes
1	Quiescent Current	I _{CC} T	No input	_	45	60	mA	_
2	Volume (Max Level)	V _{Vmax}	V _{IN} = 1 V[rms] f = 1 kHz	-1	0	1	dB	*1
3	Volume (Mid Level)	V _{Vmid}	V _{IN} = 1 V[rms] f = 1 kHz	-14.5	-12.5	-10.5	dB	*1
4	Volume (Min Level)	V _{Vmin}	V _{IN} = 1 V[rms] f = 1 kHz		-100	-90	dB	*1
5	THD (1 kHz)	THD _{max}	V _{IN} = 1 V[rms] f = 1 kHz	-116	0.1	0.3	%	*1
6	Max input level	V _{Imax}	THD = 1% f = 1 kHz	2.0	2.2	_	V[rms]	*1
7	Output noise at volume min	V _{Nmin}	$V_{IN} = 0 V[rms]$ $Rg = 4.7 k\Omega$	_	3	10	μV	*2
8	Output noise at volume max	V _{Nmax}	$V_{IN} = 0 V[rms]$ $Rg = 4.7 k\Omega$	_	65	100	μν	*2
9	Mute Level	V _{MUTE}	V _{IN} = 1 V[rms] f = 1 kHz	1/20	-100	-90	dB	*1
10	Balance (Max Level)	V _{Bmax}	V _{IN} = 1 V[rms] f = 1 kHz	-P	0	R	dB	*1
11	Balance (Min Level)	V_{Bmin}	V _{IN} = 1 V[rms] f = 1 kHz	100 ji	-82	-80	dB	*1
12	Bass (Max Level)	VB_{Bmax}	V _{IN} = 400 mV[rms] f = 50 Hz	10	12.5	15	dB	_
13	Bass (Min Level)	VB_{Bmin}	V _{IN} = 400 mV[rms] f = 50 Hz	-13.5	-11.0	-8.5	dB	_
14	Treble (Max Level)	VT _{Bmax}	V _{IN} = 400 mV[rms] f = 20 kHz	10	12.5	15	dB	_
15	Treble (Min Level)	VT_{Bmin}	V _{IN} = 400 mV[rms] f = 20 kHz	-13.5	-11.0	-8.5	dB	_
16	Super bass (Max Level)	VX _{Bmax}	V _{IN} = 400 mV[rms] f = 50 Hz	3	5	7	dB	*1
17	Super bass (Min Level)	VX_{Bmin}	V _{IN} = 400 mV[rms] f = 50 Hz	0	2	4	dB	*1

Notes) *1:DIN AUDIO filter used.

*2 : A-weighted noise filter used.

\blacksquare Electrical Characteristics (continued) at V_{CC} = 9.0 V

Note) $T_a = 25^{\circ}C \pm 2^{\circ}C$ unless otherwise specified.

В			0 :::		Limits				
No.	Parameter	Symbol	Conditions	Min	lin Typ Max		Unit	Notes	
18	AGC gain 1	V _{AGC1}	$V_{IN} = 50 \text{ mV}[\text{rms}]$ f = 1 kHz	77	110	150	mV[rms]	*1	
19	AGC gain 2	V _{AGC2}	V _{IN} = 1 V[rms] f = 1 kHz	230	345	470	mV[rms]	*1	
20	Surround level 1	V_{SU1}	V _{IN} = 50 mV[rms] f = 50 Hz	200	240	280	mV[rms]	*1	
21	Surround level 2	$ m V_{SU2}$	V _{IN} = 50 mV[rms] f = 10 kHz	130	170	210	mV[rms]	*1	
22	Surround noise Level	V _{SN}	$V_{IN} = 0 \text{ mV}$ $Rg = 4.7 \text{ k}\Omega$	-	110	150	μV[rms]	*2	
23	THD (Surround)	THD _{SU}	V _{IN} = 400 mV[rms] f = 1 kHz	, delcit	0.1	0.3	%	*1	
24	Cross talk	СТ	$V_{IN} = 1 V[rms]$ f = 1 kHz	_	-78	-66	dB	*2	
25	Channel balance (Max)	CB _{max}	V _{IN} = 1 V[rms] f = 1 kHz	<u>-1</u>	0	1	dB	*1	
26	Channel balance (1/4)	CB _{1/4}	V _{IN} = 1 V[rms] f = 1 kHz	-2	0	2	dB	*1	

Notes) *1 : DIN AUDIO filter used.

^{*2 :} A-weighted noise filter used.

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■ Electrical Characteristics (continued) at V_{CC} = 9.0 V Note) T_a = 25°C±2°C unless otherwise specified.

В	5 ,		0 1111		Limits	Lloit	Notes	
No.	Parameter	Symbol	Conditions	Min	Тур	Max	Unit	Notes
I ² C	Interface							
27	Suction current during ACK	I _{ACK}	Max. suction current value of Pin 14 at 0 4 V	3.0	10	_	mA	_
28	SCL, SDA signal input High level	V_{IHI}		3.0	_	5.0	V	_
29	SCL, SDA signal input Low level	V _{ILO}		0	_	1.5	V	_
30	Max frequency allowable to input	f_{imax}			- >	100	kbit/s	



\blacksquare Electrical Characteristics (Reference values for design) at $V_{CC} = 9.0 \text{ V}$

Note) $T_a = 25^{\circ}C\pm 2^{\circ}C$ unless otherwise specified.

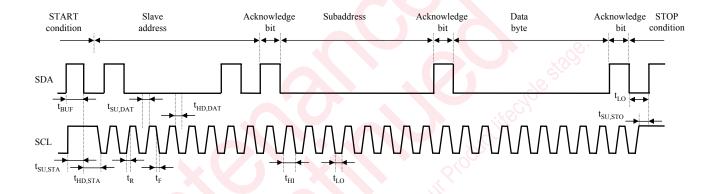
The characteristics listed below are reference values derived from the design of the IC and are not guaranteed by inspection. If a problem does occur related to these characteristics, we will respond in good faith to user concerns.

B No.	Deremeter	Cumbal	Conditions	Refe	erence va	lues	Unit	Notes	
B NO.	Parameter	Symbol	Conditions	Min	Тур	Max	Unit	140103	
I ² C in	terface								
1	Bus free before start	t _{BUF}		4.0		_	μs		
2	Set-up time of START condition	t _{SU,STA}		4.0	_	_	μs	_	
3	Hold time of START condition	t _{HD,STA}		4.0			μs	_	
4	Low period of SCL, SDA	t_{LO}		4.0	<u>-0</u> 6		μs	_	
5	High period of SCL	t _{HI}		4.0		_	μs	_	
6	SCL, SDA rise time	t_{R}		-1/19	_	1.0	μs	_	
7	SCL, SDA fall time	$t_{\rm F}$			_	0.35	μs	_	
8	Data set-up time (Write)	t _{SU,DAT}	- 04	0.25	_	_	μs	_	
9	Data hold time (Write)	t _{HD,DAT}		0	_	_	μs	_	
10	Acknowledge set-up time	t _{SU,ACK}	- ,,0,100,100		_	3.5	μs	_	
11	Acknowledge hold time	t _{HD,ACK}	- MI - S (A)	0			μs	_	
12	[STOP] condition set-up time	$t_{\rm SU,STO}$		4.0		it l	μs	_	
DAC			185 181 18 18 18 18 18 18 18 18 18 18 18 18	131	7.10	100			
13	6 bit DAC DNLE	L_6	1LSB = [Data (max) – Data (00)]/63	0.1	1.0	1.9	LSB/ STEP	_	

■ Electrical Characteristics (Reference values for design) (continued) at V_{CC} = 9 V

Note) $T_a = 25^{\circ}C \pm 2^{\circ}C$ unless otherwise specified.

The characteristics listed below are reference values derived from the design of the IC and are not guaranteed by inspection. If a problem does occur related to these characteristics, we will respond in good faith to user concerns.



\blacksquare Electrical Characteristics (Reference values for design) (continued) at $V_{CC} = 9.0 \ V$

Note) $T_a = 25^{\circ}C \pm 2^{\circ}C$ unless otherwise specified.

The characteristics listed below are reference values derived from the design of the IC and are not guaranteed by inspection. If a problem does occur related to these characteristics, we will respond in good faith to user concerns.

B No.	Parameter	Symbol	Conditions	Refe	erence va	alues	Unit	Notes	
D NO.	i alametei	Symbol	Conditions	Min Typ		Max	Offic	110103	
14	AGC gain 3 (Sub address 04H : 05H)	V _{AGC3}	$V_{IN} = 100 \text{ mV[rms]}$ f = 1 kHz	_	150	_	mV[rms]	*1	
15	AGC gain 4 (Sub address 04H : 03H)	V _{AGC4}	$V_{IN} = 140 \text{ mV}[\text{rms}]$ f = 1 kHz		200	_	mV[rms]	*1	
16	AGC gain 5 (Sub address 04H : 01H)	V _{AGC5}	$V_{IN} = 200 \text{ mV}[\text{rms}]$ f = 1 kHz		250	250X	mV[rms]	*1	
17	AGC gain 6 (Sub address 04H : 07H)	V _{AGC6}	$V_{IN} = 280 \text{ mV}[\text{rms}]$ f = 1 kHz		350	<u> </u>	mV[rms]	*1	
18	AGC gain 7 (Sub address 04H : 03H)	V _{AGC7}	V _{IN} = 500 mV[rms] f = 1 kHz	180	290	430	mV[rms]	*1	

Note) *1 : DIN AUDIO filter used.

■ Electrical Characteristics Test Procedures

С	Darameter	Cymahal			S	W			Innut conditions		Sub	addr	ess	
No.	Parameter	Symbol	1	2	3	4	5	6	Input conditions	00H	01H	02H	03H	04H
1	Quiescent Current	I _{CC} T	_	_		_	ON	OFF	$V_{IN} = 0 \text{ mV}$	FC	80	77	00	00
2	Volume (Max Level)	V _{Vmax}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 1 V[rms]$ f = 1 kHz	FC	80	77	00	00
3	Volume (Mid Level)	V_{Vmid}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 1 \text{ V[rms]}$ f = 1 kHz	80	80	77	00	00
4	Volume (Min Level)	V_{Vmin}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 1 \text{ V[rms]}$ f = 1 kHz	00	80	77	00	00
5	THD (1 kHz)	THD _{max}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 1 V[rms]$ f = 1 kHz	FC	80	77	00	00
6	Max input level	V _{Imax}	b, a	a, b	b, a	a	ON	OFF	THD = 1% f = 1 kHz	FC	80	77	00	00
7	Output noise at volume min	V _{Nmin}	c	c	b, a	b	ON	OFF	$V_{IN} = 0 \text{ mV}$ $Rg = 4.7 \text{ k}\Omega$	00	80	77	00	00
8	Output noise at volume max	V _{Nmax}	c	c	b, a	b	ON	OFF	$V_{IN} = 0 \text{ mV}$ $Rg = 4.7 \text{ k}\Omega$	FC	80	77	00	00
9	Mute Level	V _{MUTE}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 1 \text{ V[rms]}$ f = 1 kHz	FE	80	77	00	00
10	Balance (Max Level)	V _{Bmax}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 1 V[rms]$ f = 1 kHz	FC	FC, 00	77	00	00
11	Balance (Min Level)	V_{Bmin}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 1 \text{ V[rms]}$ f = 1 kHz	FC	FC, 00	77	00	00
12	Bass (Max Level)	VB_{Bmax}	b, a	a, b	b, a	c	ON	OFF	$V_{IN} = 400 \text{ mV}[\text{rms}]$ f = 50 Hz	FC	80	7F	00	00
13	Bass (Min Level)	VB_{Bmin}	b, a	a, b	b, a	c	ON	OFF	$V_{IN} = 400 \text{ mV}[\text{rms}]$ f = 50 Hz	FC	80	70	00	00
14	Treble (Max Level)	VT_{Bmax}	b, a	a, b	b, a	c	ON	OFF	$V_{IN} = 400 \text{ mV}[\text{rms}]$ f = 20 kHz	FC	80	F7	00	00
15	Treble (Min Level)	VT_{Bmin}	b, a	a, b	b, a	ç	ON	OFF	$V_{IN} = 400 \text{ mV[rms]}$ f = 20 kHz	FC	80	07	00	00
16	Super bass (Max Level)	VX _{Bmax}	b, a	a, b	b, a	c	ON	OFF	$V_{IN} = 400 \text{ mV[rms]}$ $f = 50 \text{ Hz}$	FD	80	77	00	00
17	Super bass (Min Level)	VX_{Bmin}	b, a	a, b	b, a	c	ON	OFF	$V_{IN} = 400 \text{ mV}[\text{rms}]$ $f = 50 \text{ Hz}$	FD	83	77	00	00

■ Electrical Characteristics Test Procedures (continued)

С	Darameter	Cumhal			S	W			Innut conditions	Sub address				
No.	Parameter	Symbol	1	2	3	4	5	6	Input conditions	00H	01H	02H	03H	04H
18	AGC gain 1	V _{AGC1}	b, a	a, b	a, b	a	ON	OFF	$V_{IN} = 50 \text{ mV}[\text{rms}]$ f = 1 kHz	FC	80	77	00	03
19	AGC gain 2	V _{AGC2}	b, a	a, b	a, b	a	ON	OFF	$V_{IN} = 1 \text{ V[rms]}$ f = 1 kHz	FC	80	77	00	03
20	Surround level 1	V _{SU1}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 50 \text{ mV}[\text{rms}]$ f = 50 Hz	FC	80	77	80	00
21	Surround level 2	V _{SU2}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 50 \text{ mV[rms]}$ f = 10 kHz	FC	80	77	80	00
22	Surround noise Level	V _{SN}	c	c	b, a	ь	ON	OFF	$V_{IN} = 0 \text{ mV[rms]}$ $Rg = 4.7 \text{ k}\Omega$	FC	80	77	80	00
23	THD (Surround)	THD _{SU}	b, a	a, b	a	a	ON	OFF	$V_{IN} = 400 \text{ mV[rms]}$ f = 1 kHz	FC	80	77	80	00
24	Cross talk	СТ	b, a	a, b	a, b	b	ON	OFF	$V_{IN} = 1 V[rms]$ f = 1 kHz	FC	80	77	00	00
25	Channel balance (Max)	CB _{max}	=(ON	OFF	$V_{IN} = 1 \text{ V[rms]}$ f = 1 kHz	FC	80	77	00	00
26	Channel balance (1/4)	CB _{1/4}					ON	OFF	$V_{IN} = 1 \text{ V[rms]}$ f = 1 kHz	40	80	77	00	00

■ Electrical Characteristics (Reference values for design) Test Procedures

С	Parameter	Symbol	SW						Innut conditions	Sub address				
No.	Parameter	Symbol	1	2	3	4	5	6	Input conditions	00H	01H	02H	03H	04H
14	AGC gain 3	V _{AGC3}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 100 \text{ mV}[\text{rms}]$ f = 1 kHz	FC	80	77	00	05
15	AGC gain 4	V _{AGC4}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 140 \text{ mV}[\text{rms}]$ f = 1 kHz	FC	80	77	00	03
16	AGC gain 5	V _{AGC5}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 200 \text{ mV}[\text{rms}]$ f = 1 kHz	FC	80	77	00	01
17	AGC gain 6	V _{AGC6}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 280 \text{ mV[rms]}$ f = 1 kHz	FC	80	77	00	07
18	AGC gain 7	V _{AGC7}	b, a	a, b	b, a	a	ON	OFF	$V_{IN} = 500 \text{ mV}[\text{rms}]$ f = 1 kHz	FC	80	77	00	03

■ Technical Data

• I/O block circuit diagrams and pin function descriptions

Note) The characteristics listed below are reference values derived from the design of the IC and are not guaranteed.

Pin No.	Waveform and voltage	Internal circuit	Description
1	4.5 V	5k 2k	Phase filter 1
2	Depend on input level 0.5 V to 2.0 V	Level 2 Level 1 1k U50kU2k 2	AGC level sensor
3	4.5 V	3 1.5k 1/2 V _{CC}	L-ch. input
4	4.5 V	4 2.5k	Phase filter 2
5	4.5 V	3 2k 2k 2k 2.5k 1	Phase filter 3

• I/O block circuit diagrams and pin function descriptions (continued)

Note) The characteristics listed below are reference values derived from the design of the IC and are not guaranteed.

Pin No.	Waveform and voltage	Internal circuit	Description
6	4.5 V	6 5k 2k	Phase filter 4
7	0 V		GND
8	4.5 V	8 900	L-ch. Treble Fc adjustment
9	4.5 V	8.64k 1.36k ————————————————————————————————————	L-ch. Bass Fc adjustment
10	Depend on I ² C data 1.6 V to 2.5 V	250 19.4k 72.0 V	Bass DAC output

• I/O block circuit diagrams and pin function descriptions (continued)

Note) The characteristics listed below are reference values derived from the design of the IC and are not guaranteed.

Pin No.	Waveform and voltage	Internal circuit	Description
11	Depend on I ² C data 2.0 V to 4.0 V	3.5 V 11k 600	Volume DAC output
12	4.5 V	250	L-ch. output
13		2k	I ² C bus clock input
14	-	2k 15p	I ² C bus data input
15	4.5 V	250	R-ch. output

• I/O block circuit diagrams and pin function descriptions (continued)

Note) The characteristics listed below are reference values derived from the design of the IC and are not guaranteed.

Pin No.	Waveform and voltage	Internal circuit	Description
16	Depend on I ² C data 1.6 V to 2.5 V	250 16 250 19.4k	Treble DAC output
17	Depend on I ² C data 2.5 V to 3.5 V	3.5 V 15k (17) 250 250 250 250	Balance DAC output
18	4.5 V	18 900 6.3k	R-ch. Treble Fc adjustment
19	4.5 V	8.64k 11.36k	R-ch. Bass Fc adjustment
20	4.5 V	2.2k 2k 2k	Bass mix gain adjustment

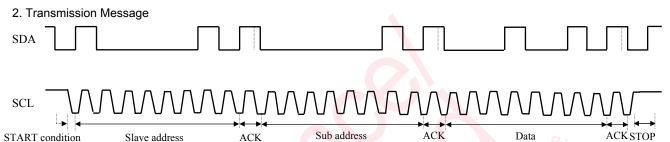
• I/O block circuit diagrams and pin function descriptions (continued)

Note) The characteristics listed below are reference values derived from the design of the IC and are not guaranteed.

Pin No.	Waveform and voltage	Internal circuit	Description
21	4.5 V	21 70k 500 70k	Reference voltage stabilizing
22	4.5 V	22 1.5k 1/2V _{CC}	R-ch. input
23	9.0 V	- "iges "ilitelings"	V_{CC}
24	Depend on I ² C data 0.6 V to 2.6 V	30.8k 24	Mode control

■ Technical Data (continued)

• I2C-bus



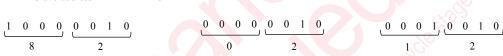


Fig.1 Example of transmission message

For transmission messages, both SCL and SDA are transferred in the form of synchronized serial transmission.

SCL is a clock of a specific frequency, and SDA indicates address data for controlling the receiving side and is transferred in parallel, being synchronized with SCL.

Data is transferred in principle in 3 octets (bytes), and each one octet (one octet = 8 bits) includes one acknowledge bit.

Frame structure is described below.

(a) START condition

The receiver becomes possible to receive data when SDA changes from High to Low while SCL is High.

(b) STOP condition

The receiver halts receiving when SDA changes from Low to High while SCL is High.

(c) Slave address

This is an address which is determined for each device. If other device address is sent, receiving will be halted.

(d) Sub address

This is an address which is determined for each function.

(e) Data

This is control data.

(f) Acknowledge bit

This is a bit by which the master acknowledges that data was successfully received in each octet. Master sends the High signal and the receiver sends back the Low signal as shown in Figure 1 with dotted line, causing the master to acknowledge the reception by the receiver. If the Low signal is not returned, communication will be halted. Except START and STOP conditions, SDA does not change while SCL is High.

SDB00169AEB 22

condition

■ Technical Data (continued)

- I2C-bus (continued)
- 3. I2C Bus Addressing
 - (1) This contains 7 DAC controls and 4 SWs.
 - (2) オートインクリメント機能は以下のとおりです。
 - Sub address 0xxxxxxx : Auto-increment mode

(When the data is sent in consecutive order, the Sub address will be changed in consecutive order, as data is input.)

• Sub address 1xxxxxxx : Data update mode (When the data is sent consecutively, it is sent to the same Sub address.)

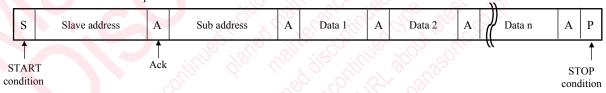
(3) I²C bus protocol

• Slave address: 10000010 (82H)

• Format (Usual)



• Auto increment mode/Data update mode



(4) Since the DAC initial status is not guaranteed, the standard data input is certainly necessary when power is turned ON.

■ Technical Data (continued)

- I²C-bus (continued)
- 3. I²C Bus Addressing (continued)
 - (5) Sub address byte and data byte format

Sub	Upper MSB Data byte								
address	D7	D6	D5	D4	D3	D2	D1	D0	
00								Super Bass ON/OFF	
01	Balance BASS Mix Effect								
02	L/R Treble L/R Bass						•		
03	MODE × × Surround E.						d Effect		
04	Not defined				\$100	AGC	ADJ	AGC ON/OFF	

1) MODE

"00" = Bypass

"01" = Simulated Stereo

"10" = Stereo Surround

"11" = Mono surround

2) Volume

DATA = "0000000" : min

DATA = "111111" : max

3) Balance

DATA = "000000" : Lout : min, Rout : max

DATA = "100000" : CENTER

DATA = "111111" : Lout : max, Rout : min

4) L/R Treble, Bass

DATA = "0000" : min

DATA = "0111" : CENTER

DATA = "1111" : max

5) Mute ON/OFF

DATA = "0" : OFF

DATA = "1" : ON

6) Bass Mix ON/OFF

DATA = "0" : OFF

DATA = "1" : ON

7) Bass Mix Effect

DATA = "11" : min

DATA = "00" : max

8) AGC ON/OFF

DATA = "0" : OFF

DATA = "1" : ON

9) AGC ADJ (0 dB Adjustment) *

DATA = "00" : 200 mV[rms]

DATA = "01" : 140 mV[rms]

DATA = "10" : 100 mV[rms]

DATA = "11" : 280 mV[rms]

10) Surround Effect

DATA = "1111" : min

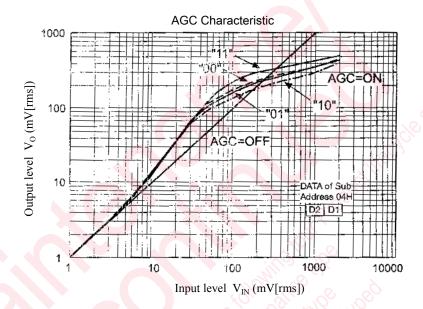
DATA = "0000" : max

Note) *: 0 dB Adjustment level of AGC is reference value, and not guaranteed by shipping inspection.

■ Technical Data (continued)

• Adjust method of AGC control

AGCがONの場合,入出力ゲインは小信号レベルにおいては0dB,標準信号レベルでは上昇し,大信号レベルでは減少します。また,AGCの入出力特性は下記のとおり I^2C によって制御できます。



■ Usage Notes

- Special attention and precaution in using
- 1. This IC is intended to be used for general electronic equipment [Television].
 - Consult our sales staff in advance for information on the following applications:
 - Special applications in which exceptional quality and reliability are required, or if the failure or malfunction of this IC may directly jeopardize life or harm the human body.
 - · Any applications other than the standard applications intended.
 - (1) Space appliance (such as artificial satellite, and rocket)
 - (2) Traffic control equipment (such as for automobile, airplane, train, and ship)
 - (3) Medical equipment for life support
 - (4) Submarine transponder
 - (5) Control equipment for power plant
 - (6) Disaster prevention and security device
 - (7) Weapon
 - (8) Others: Applications of which reliability equivalent to (1) to (7) is required
- 2. Pay attention to the direction of LSI. When mounting it in the wrong direction onto the PCB (printed-circuit-board), it might smoke or ignite.
- 3. Pay attention in the PCB (printed-circuit-board) pattern layout in order to prevent damage due to short circuit between pins. In addition, refer to the Pin Description for the pin configuration.
- 4. Perform a visual inspection on the PCB before applying power, otherwise damage might happen due to problems such as a solder-bridge between the pins of the semiconductor device. Also, perform a full technical verification on the assembly quality, because the same damage possibly can happen due to conductive substances, such as solder ball, that adhere to the LSI during transportation.
- 5. Take notice in the use of this product that it might break or occasionally smoke when an abnormal state occurs such as output pin-V_{CC} short (Power supply fault), output pin-GND short (Ground fault), or output-to-output-pin short (load short).
 And, safety measures such as an installation of fuses are recommended because the extent of the above-mentioned damage and smoke emission will depend on the current capability of the power supply.
- 6. When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not to exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.
 - Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
- 7. When using the LSI for new models, verify the safety including the long-term reliability for each product.
- 8. When the application system is designed by using this LSI, be sure to confirm notes in this book. Be sure to read the notes to descriptions and the usage notes in the book.

Request for your special attention and precautions in using the technical information and semiconductors described in this book

- (1) If any of the products or technical information described in this book is to be exported or provided to non-residents, the laws and regulations of the exporting country, especially, those with regard to security export control, must be observed.
- (2) The technical information described in this book is intended only to show the main characteristics and application circuit examples of the products. No license is granted in and to any intellectual property right or other right owned by Panasonic Corporation or any other company. Therefore, no responsibility is assumed by our company as to the infringement upon any such right owned by any other company which may arise as a result of the use of technical information described in this book.
- (3) The products described in this book are intended to be used for standard applications or general electronic equipment (such as office equipment, communications equipment, measuring instruments and household appliances).
 - Consult our sales staff in advance for information on the following applications:
 - Special applications (such as for airplanes, aerospace, automobiles, traffic control equipment, combustion equipment, life support systems and safety devices) in which exceptional quality and reliability are required, or if the failure or malfunction of the products may directly jeopardize life or harm the human body.
 - · Any applications other than the standard applications intended.
- (4) The products and product specifications described in this book are subject to change without notice for modification and/or improvement. At the final stage of your design, purchasing, or use of the products, therefore, ask for the most up-to-date Product Standards in advance to make sure that the latest specifications satisfy your requirements.
- (5) When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not to exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.
- Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
- (6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.
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